



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20260612000.1
Qualification of RFAB as additional Fab Site, Die Revision and
CDAT as additional Assembly Site for select devices
Change Notification / Sample Request**

Date: June 15, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the lifetime buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260612000.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC8T245RHRLR	NULL
74LVC8T245RHRLRG4	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260612000.1	PCN Date:	June 15, 2026
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Title: Qualification of RFAB as additional Fab Site, Die Revision, and TI Chengdu as additional Assembly Site for select devices

Customer Contact: Change Management team **Dept:** Quality Services

Proposed 1st Ship Date: September 13, 2026 **Sample requests accepted until:** August 14, 2026

***Sample requests received after August 14, 2026 will not be supported.**

Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option and TI CDAT as additional Assembly site options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter
FFAB	ASL3C	200mm	RFAB	LBC9	300mm

Construction differences are as follows:

	Current	Additional
Assembly Site	MLA	CDAT
Bond Wire composition/diameter	Cu, 0.96 mil	Cu, 1.0 mil
Mold Compound	4208625	4222198
Mount Compound	4205846	4207123
Marking	No ECAT Marking	G4

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



SN74LVC8T245
SCES584D – JUNE 2005 – REVISED MAY 2026

• Updated DB package in the Package Information table.....	1
• Updated ICCA/ ICCB values in the <i>Electrical Characteristics</i> section.....	9
• Added V _{CC} isolation information.....	14
• Added Section 7.3.3	14
• Updated the <i>Power Supply Recommendations</i> section.....	17



SN74LVC8T245
SCES584C – JUNE 2005 – REVISED DECEMBER 2022

Changes from Revision B (November 2014) to Revision C (December 2022)	Page
• Removed Machine Model specification.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Updated the <i>ESD Ratings</i> section (was called <i>Handling Ratings</i>).....	4
• Updated thermals in the Thermal Informations section.	6
• Increased max switching characteristics specs for $V_{CCB} = 5V$	8
• Updated the <i>Overview</i> section.....	12
• Added the <i>Balanced High-Drive CMOS Push-Pull Outputs</i> and <i>V_{CC} Isolation</i> sections.....	12
• Updated the <i>Power Supply Recommendations</i> section.....	15

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74LVC8T245	SCES584C	SCES584D	SN74LVC8T245 data sheet, product information and support TI.com

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the updated Standard Data Packet for more details on the changes.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If the boxes below are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

Changes to product identification resulting from this PCN:

Wafer Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
RFAB	RFB	USA	Richardson

Current

New

Die Rev [2P]	Die Rev [2P]
-	A

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
Malaysia	MLA	MYS	Kuala Lumpur
TI Chengdu	CDA	CHN	Chengdu

Sample product shipping label (not actual product label):

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 8033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

SN74LVC8T245RHRLR | 74LVC8T245RHRLRG4

Qualification Data

Qualification Report
 Approve Date 31-MARCH -2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC8T245RHRLR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: CAXC8T245QRHLRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	1/7 7/0	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	1/7 7/0	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/7 7/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	1/7 7/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/7 6/0	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/7 6/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/3/0/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0

- QBS: Qual By Similarity
- Qual Device SN 74LVC8T245RHRLR is qualified at MSL 1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2110-043

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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